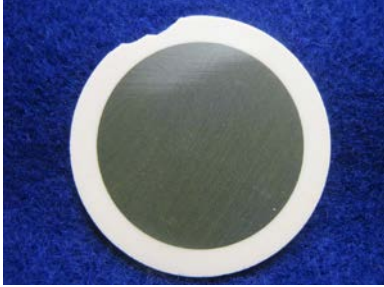
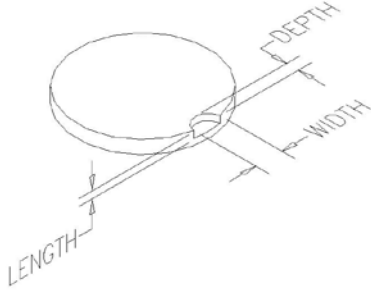

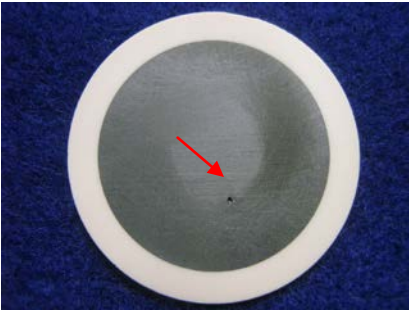


Inspection Method Sheet

Part Number: Generic
Drawing Number: Generic
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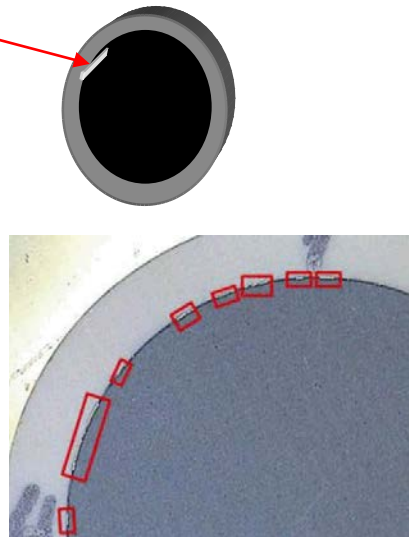
Part Name: Assemblies
Operation: Final Inspection
Written By: Anna Huse
Date: 5/1/01

Applicable customer specifications take precedence over this procedure (reference customer drawing).

Description / Dimensions	Picture / Detail	Sample Size / Method / Standard
<p>1) Inspection for Chips (Material broken off an edge or a corner):</p> <p>No more than 3 chips per part. Any chip under .020" is not recognized. The depth of the chip cannot exceed ½ of the parts thickness.</p> <p>Part Size – 1.00" and under No single edge chip \geq .075" in length and width.</p> <p>Part Size – Over 1.00" No single edge chip \geq .100" in length and width.</p>	 	<p>Method: Visual using a 4X illuminated magnification or greater.</p> <p>Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p>2) Inspection for Holes (A pit on the surface of the part):</p> <p>No more than 2 holes per part</p> <p>Part Size – 1.00" and under No hole to exceed .030".</p> <p>Part Size – Over 1.00" No hole to exceed .040"</p>	 	<p>Method: Visual using a 4X illuminated magnification or greater.</p> <p>Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>

3) Inspection for Air-gaps and Glue-gaps (A gap between the assembly):

Air gaps are acceptable if they do not exceed 40% of the ferrite circumference.



Method: Visual using a 4X illuminated magnification or greater.

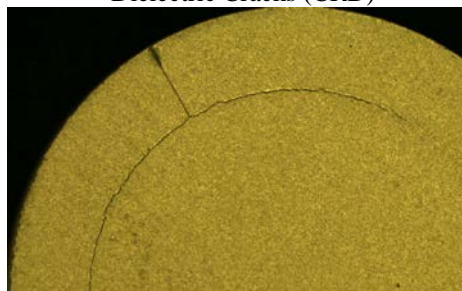
Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

4) Inspection for Cracks and Laminations:

None allowed



Dielectric Cracks (CRD)



Method: Visual using a 4X illuminated magnification or greater.

Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

5) Inspection for Material Imperfections (Kiln Reaction, Large Grains, Contamination):

None allowed

Not Acceptable

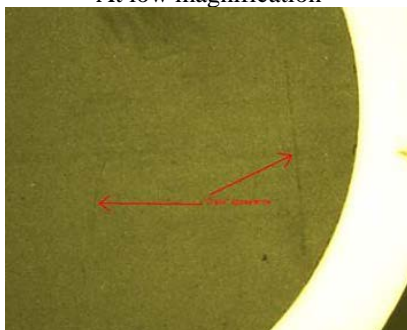


Method: Visual using a 4X illuminated magnification or greater.

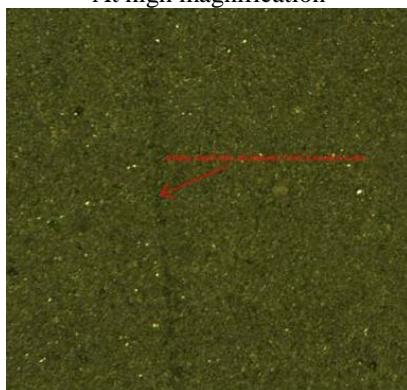
Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

Minor scratches are Acceptable

At low magnification



At high magnification



6) Inspection for Blemishes (A discoloration in the material):

No more than 3 blemishes per part

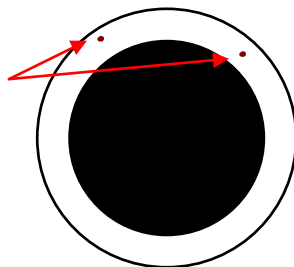
Part Size – 1.00” and under

No blemish to exceed .030”.

Part Size – Over 1.00”

No blemish to exceed .040”

No blemishes allow if they create a hole.



Method: Visual using a 4X illuminated magnification or greater.

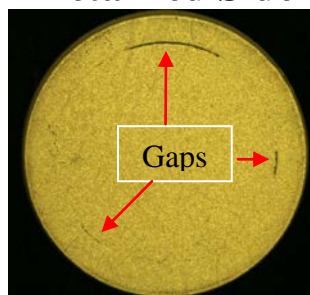
Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

7) Inspection for Gaps:

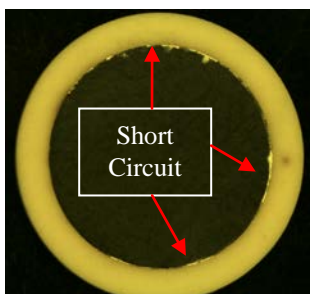
Gaps: are acceptable as long as there is no “ Short Circuit” (see *NonMetallized Side*). When Gaps are detected, Visual Inspection shall be performed on the non-metalized side for any silver spots or trace through the Gap that create “Short Circuit”.

Short Circuit: Silver spots or trace on the non-metalized side at the interface area of the Dielectric Ring and Magnetic Disk.

Metalized Side



Non Metalized Side



Method: Visual using a 4X illuminated magnification or greater.

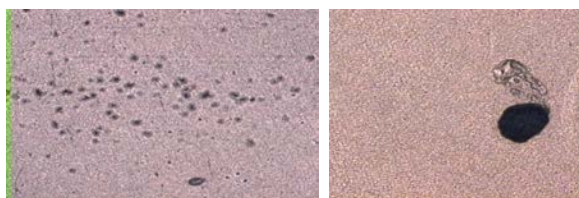
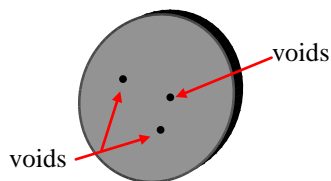
Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

8) Inspection for Voids (a hole) and Divots (a dent) in the metallization surface.

For Voids:

No voids $\geq .040$ ”

No more than 5 voids per part.



Method: Visual using a 4X illuminated magnification or greater.

Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

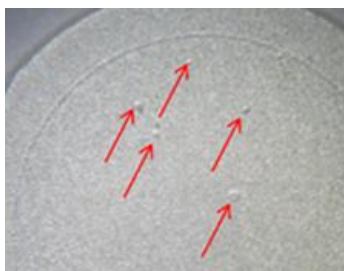
Continue from section 8:

For Divots:

No divot $\geq .100$ ”


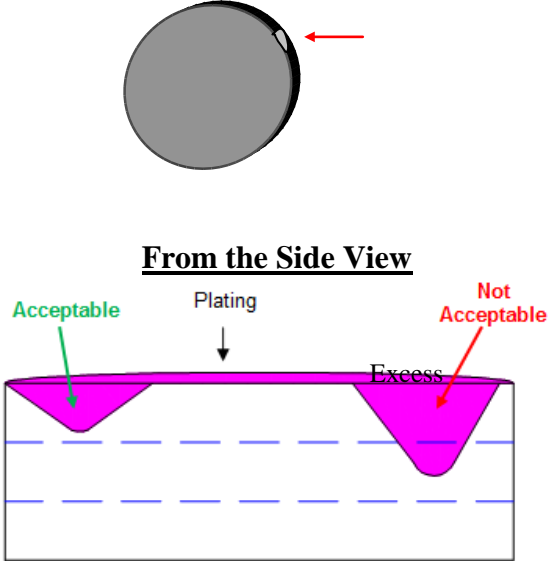
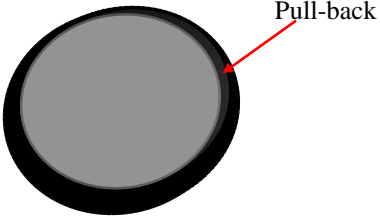
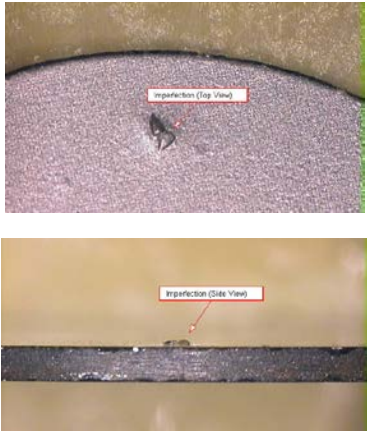
No more than 5 divots per part.

Note: No more than 5 of each defect allowed per part



Method: Visual using a 4X illuminated magnification or greater.

Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.

<p>9) Inspection for Excess metal on non-metalized surface:</p> <p>No metal > 0.025" in greatest dimension allowed.</p>		<p>Method: Visual using a 4X illuminated magnification or greater.</p> <p>Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p>10) Inspection of excess metal on the O.D./edge:</p> <ol style="list-style-type: none"> No bridging allowed between top and bottom surfaces Parts are allowed to have excess metal on 1/3 of the thickness. Metal specks not allowed below 2/3 of the part thickness as measure from the metalized side. 		<p>Method: Visual using a 4X illuminated magnification or greater.</p> <p>Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p>11) Inspection for Pull-back (the ceramic gap between the edge of the part and where the metal begins on the metalized surface):</p> <p>All Part Sizes The pull back can not be >0.015"</p>		<p>Method: Visual using a 4X illuminated magnification or greater.</p> <p>Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p>12) Inspection for visual imperfections on the metallized surface:</p> <ul style="list-style-type: none"> No surface imperfections, blisters, debris, excess metal etc. > 0.040" in greatest dimension No discernable surface condition that alters the surface uniformity by producing visible peaks and build-up 		<p>Method: Visual using a 4X illuminated magnification or greater.</p> <p>Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>